

MITSUBISHI LSIs

M5M5179P-35, -45, -55

73728-BIT (8192-WORD BY 9-BIT) CMOS STATIC RAM

DESCRIPTION

This is a family of 8192 word by 9-bit static RAMs, fabricated with the high performance CMOS silicon gate MOS process and designed for high-speed application. 9 bit organization is useful for parity check system. These devices operate on a single 5V supply, and are directly TTL compatible.

FEATURES

- Fast access time M5M5179P-35 35ns (max.)
M5M5179P-45 45ns (max.)
M5M5179P-55 55ns (max.)
- 9 bit organization
- Single +5V Power Supply
- Fully Static Operation: No Clocks, No Refresh
- Directly TTL Compatible: All Inputs and Outputs
- Three-State Outputs: OR-tie Capability
- Simple Memory Expansion by \overline{S}_1 , S_2
- \overline{OE} Prevents Data Contention in The I/O Bus
- Common Data I/O
- 300 mil package

APPLICATION

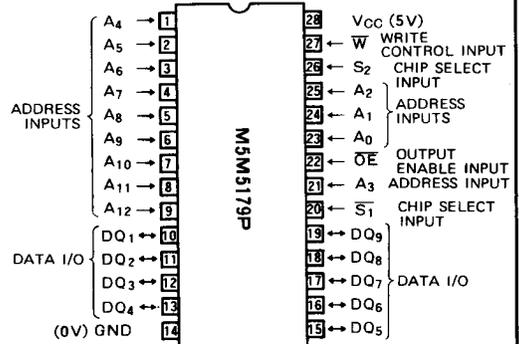
High-Speed memory system

FUNCTION

The operation mode of the M5M5179P is determined by a combination of the device control inputs \overline{S}_1 , S_2 , \overline{W} and \overline{OE} . Each mode is summarized in the function table. (see next page)

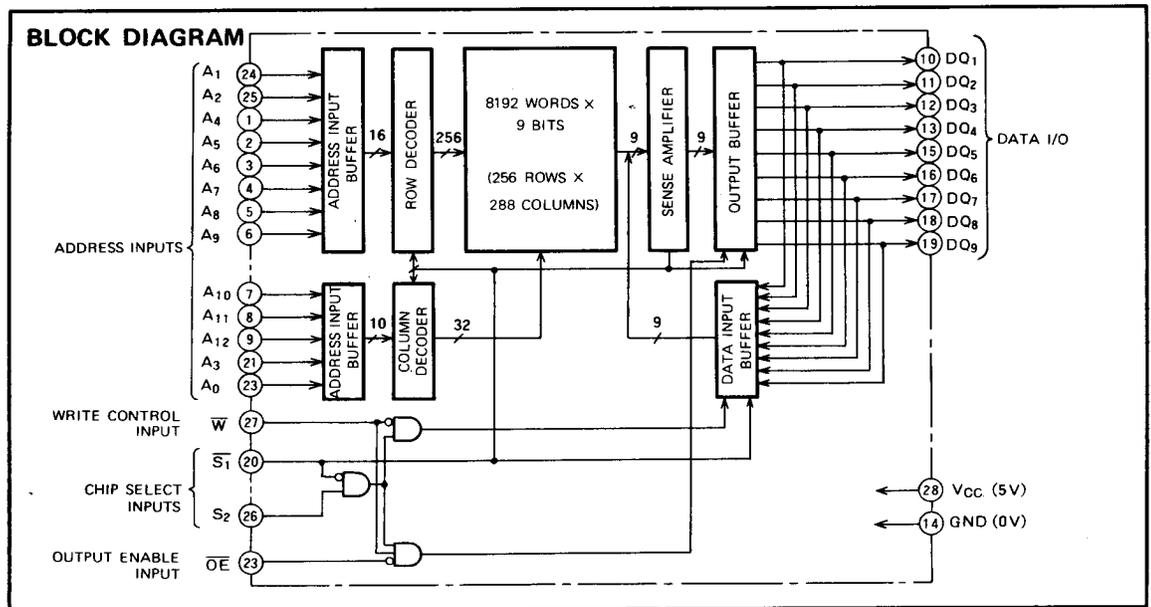
A write cycle is executed whenever the low level \overline{W} overlaps with the low level \overline{S}_1 and the high level S_2 . The

PIN CONFIGURATION (TOP VIEW)



Outline 28P4Y

address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of \overline{W} , \overline{S}_1 or S_2 , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable input \overline{OE} directly controls the output stage. Setting the \overline{OE} at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.



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A read cycle is executed by setting \overline{W} at a high level and \overline{OE} at a low level while $\overline{S_1}$ and S_2 are in an active state ($\overline{S_1} = L, S_2 = H$)

When setting $\overline{S_1}$ at a high level, the chip is in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by $\overline{S_1}$. The power supply current is reduced as low as the stand-by current which is specified as I_{CC2} or I_{CC3} .

FUNCTION TABLE

$\overline{S_1}$	S_2	\overline{W}	\overline{OE}	Mode	DQ	I_{CC}
L	L	X	X	Non selection	high-impedance	Active
H	X	X	X	Non selection	high-impedance	Standby
L	H	L	X	Write	D_{IN}	Active
L	H	H	L	Read	D_{OUT}	Active
L	H	H	H		high-impedance	Active

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	Supply voltage	With respect to GND	-0.3 ~ 7	V
V_I	Input voltage		-0.3 ~ $V_{CC} + 0.3$	V
V_O	Output voltage		0 ~ V_{CC}	V
P_d	Power dissipation	$T_a = 25^\circ C$	1000	mW
T_{opr}	Operating temperature		-10 ~ 85	$^\circ C$
T_{stg}	Storage temperature		-65 ~ 150	$^\circ C$

DC ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 70^\circ C$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V_{IH}	High input voltage		2.2		$V_{CC} + 0.3$	V
V_{IL}	Low input voltage		-0.3		0.8	V
V_{OH}	High output voltage	$I_{OH} = -4\text{mA}$	2.4			V
V_{OL}	Low output voltage	$I_{OL} = 8\text{mA}$			0.4	V
I_I	Input current	$V_I = 0 \sim V_{CC}$			± 1	μA
I_{OZH}	High level output current in off-state	$\overline{S_1} = V_{IH}$ or $S_2 = V_{IL}$ or $\overline{OE} = V_{IH}$			1	μA
I_{OZL}	Low level output current in off-state	$V_{I/O} = 0 \sim V_{CC}$			-1	μA
I_{CC1}	Active supply current	$\overline{S_1} = V_{IL}$ Output open Other inputs = V_{IH}			120	mA
I_{CC2}	Stand by supply current	$S_2 = V_{IL}, \overline{S_1} = V_{IH}, \text{Other inputs} = 0 \sim V_{CC}$			25	mA
I_{CC3}	Stand by supply current	$\overline{S_1} \geq V_{CC} - 0.2V$ Other inputs $\leq 0.2V$ or $V_{CC} - 0.2V$			2	mA
C_1	Output capacitance ($T_a = 25^\circ C$)	$\overline{S_1}, S_2, \overline{OE}, \overline{W}$			7	pF
		$A_0 \sim A_{12}$	$V_I = GND, V_I = 25\text{mVrms}, f = 1\text{MHz}$		6	
C_0	Output capacitance ($T_a = 25^\circ C$)	$V_O = GND, V_O = 25\text{mVrms}, f = 1\text{MHz}$			8	pF

Note 1 Direction for current flowing into IC is indicated as positive (no mark)
 2 Typical value is $V_{CC} = 5V, T_a = 25^\circ C$



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SWITCHING CHARACTERISTICS ($T_a = 0 - 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

Read cycle

Symbol	Parameter	Limits									Unit
		M5M5179P-35			M5M5179P-45			M5M5179P-55			
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{CR}	Read cycle time	35			45			55			ns
$t_{a(A)}$	Address access time			35			45			55	ns
$t_{a(S1)}$	Chip select 1 access time			35			45			55	ns
$t_{a(S2)}$	Chip select 2 access time			20			25			30	ns
$t_{a(OE)}$	Output enable access time			15			20			25	ns
$t_{dis(S1)}$	Output disable time after $\overline{S_1}$ high			20			25			35	ns
$t_{dis(S2)}$	Output disable time after S_2 low			20			25			35	ns
$t_{dis(OE)}$	Output disable time after \overline{OE} high			20			25			35	ns
$t_{en(S1)}$	Output enable time after $\overline{S_1}$ low	5			5			5			ns
$t_{en(S2)}$	Output enable time after S_2 high	3			3			3			ns
$t_{en(OE)}$	Output enable time after \overline{OE} low	3			3			3			ns
$t_{V(A)}$	Data valid time after address change	3			3			3			ns

TIMING REQUIREMENTS ($T_a = 0 - 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

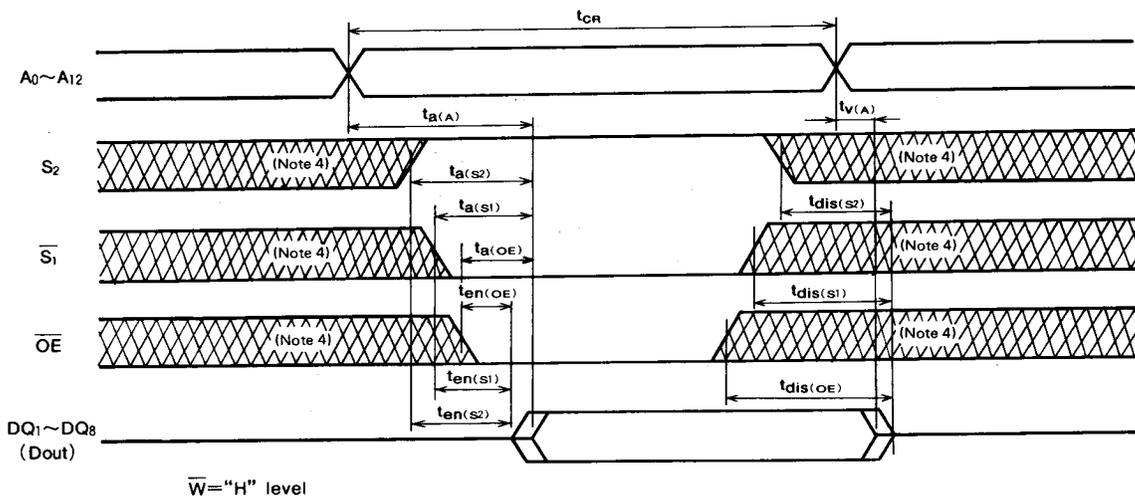
Write cycle

Symbol	Parameter	Limits									Unit
		M5M5179P-35			M5M5179P-45			M5M5179P-55			
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{CW}	Write cycle time	35			45			55			ns
$t_{w(W)}$	Write pulse width	20			25			30			ns
$t_{su(A)}$	Address set up time	0			0			0			ns
$t_{su(S1)}$	Chip select 1 set up time	30			40			45			ns
$t_{su(S2)}$	Chip select 2 set up time	20			25			30			ns
$t_{su(D)}$	Data set up time	17			20			30			ns
$t_h(D)$	Data hold time	0			0			0			ns
$t_{rec(W)}$	Write recovery time	3			3			3			ns
$t_{dis(W)}$	Output disable time after \overline{W} low			20			20			20	ns
$t_{dis(OE)}$	Output disable time after \overline{OE} high			15			25			25	ns
$t_{en(W)}$	Output enable time after \overline{W} high	0			0			0			ns
$t_{en(OE)}$	Output enable time after \overline{OE} low	3			3			3			ns

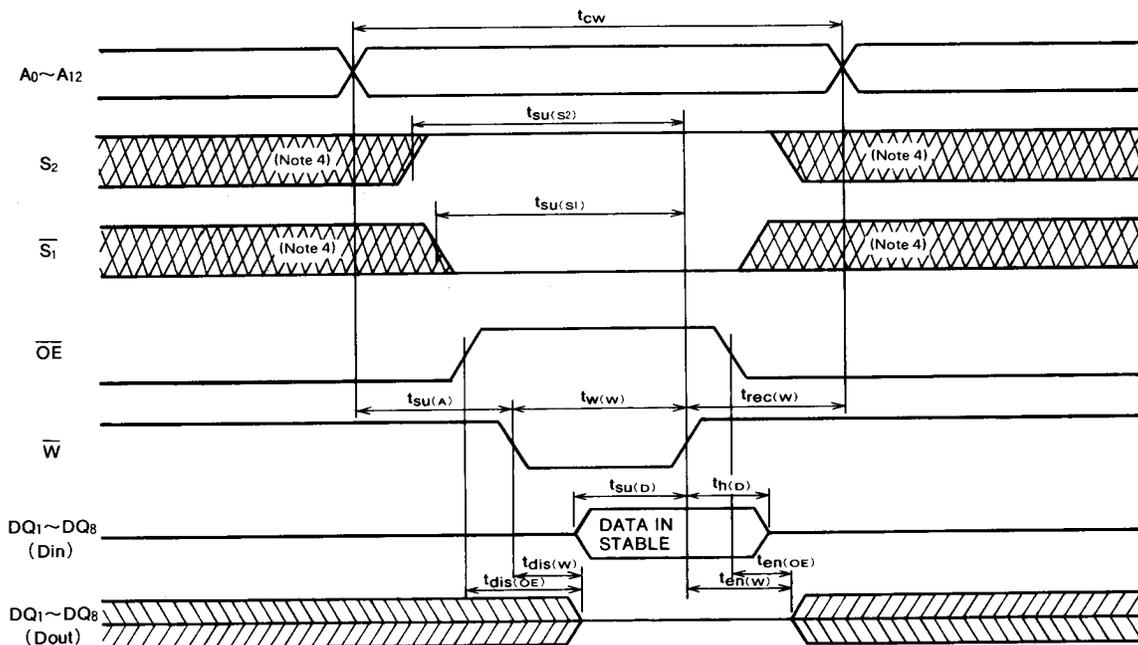
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TIMING DIAGRAM

Read cycle

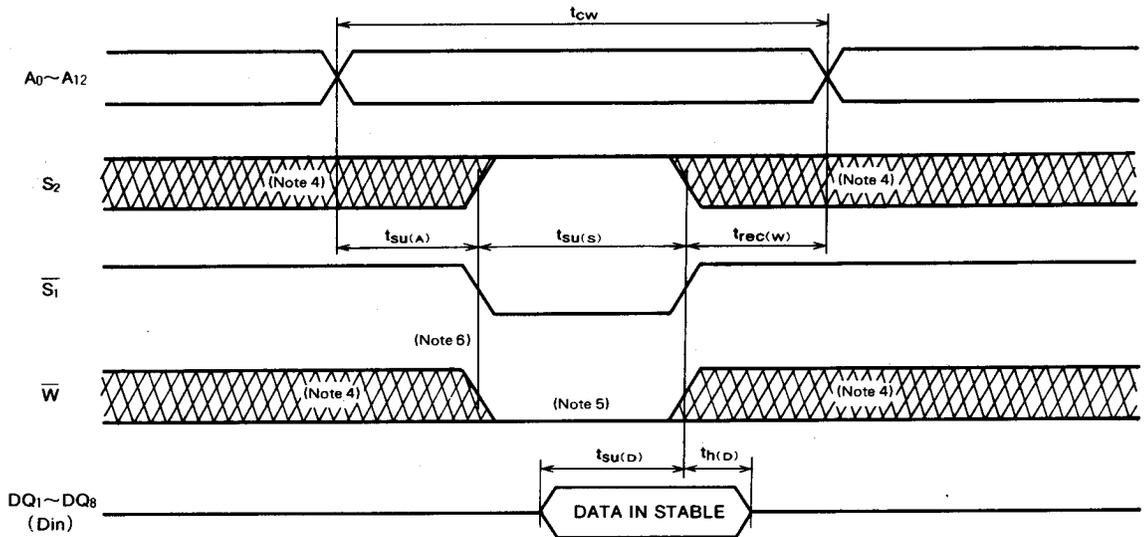


Write cycle (\bar{W} control)



73728-BIT (8192-WORD BY 9-BIT) CMOS STATIC RAM

Write cycle (\bar{S} control)



CONDITIONS

- Input pulse levels 0 to 3V
- Input rise and fall time 5ns
- Input timing reference level 1.5V
- Output timing reference level 0.8V ~ 2V
- Output loads Fig. 1, Fig. 2

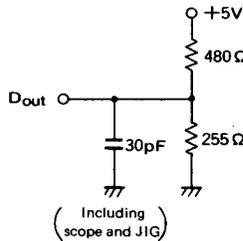


Fig. 1 Output load

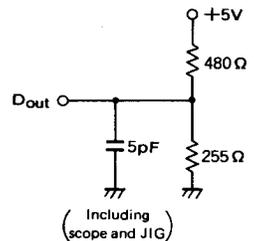


Fig. 2 Output load for t_{en} t_{dis}

- Note 4: Hatching indicates the state is don't care.
- 5. Writing is executed while \bar{S}_2 high overlaps \bar{S}_1 and \bar{W} low.
- 6. If \bar{W} goes low simultaneously with or prior to \bar{S}_1 low or \bar{S}_2 high, the output remains in the high-impedance state.
- 7. Don't apply inverted phase signal externally when DQ pin is in output mode.